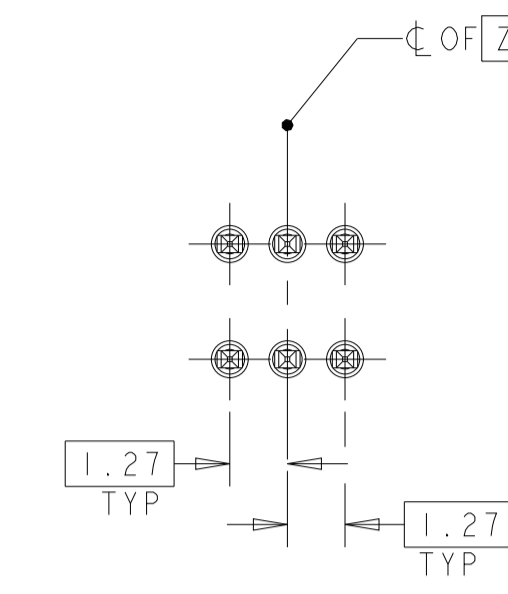
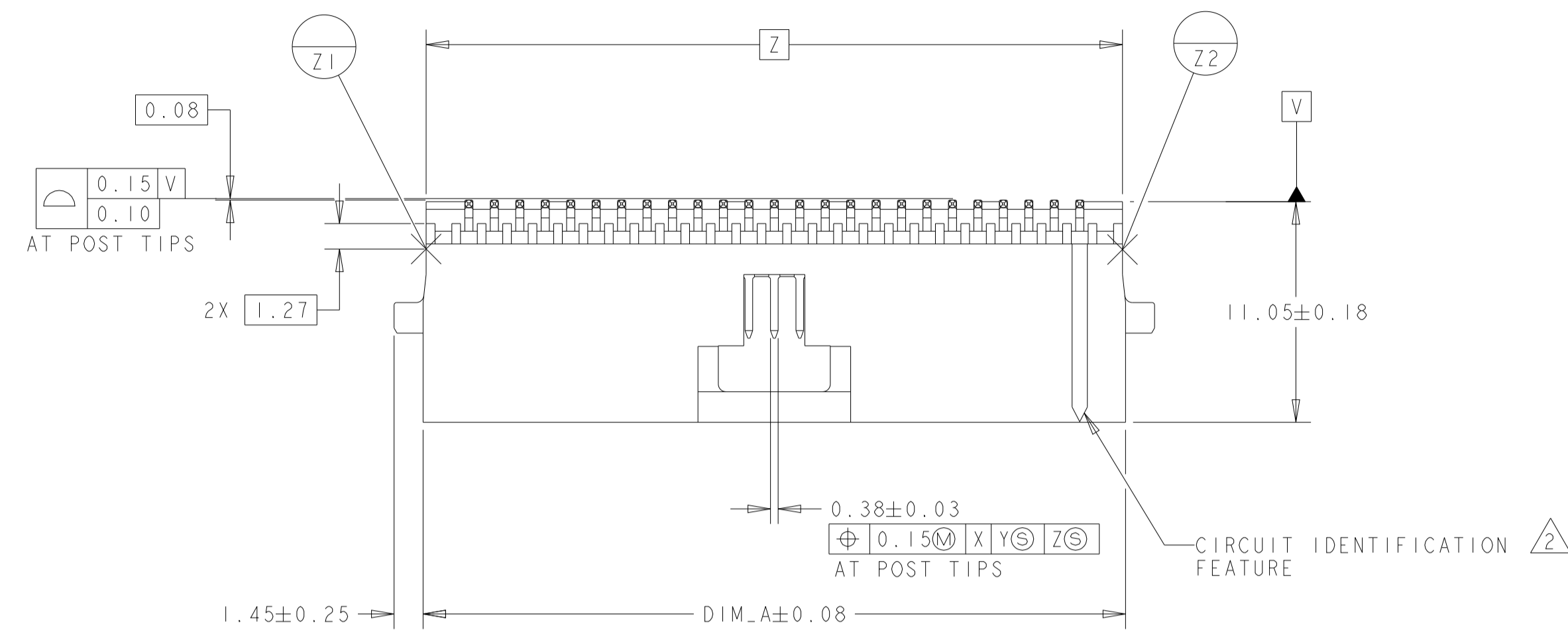
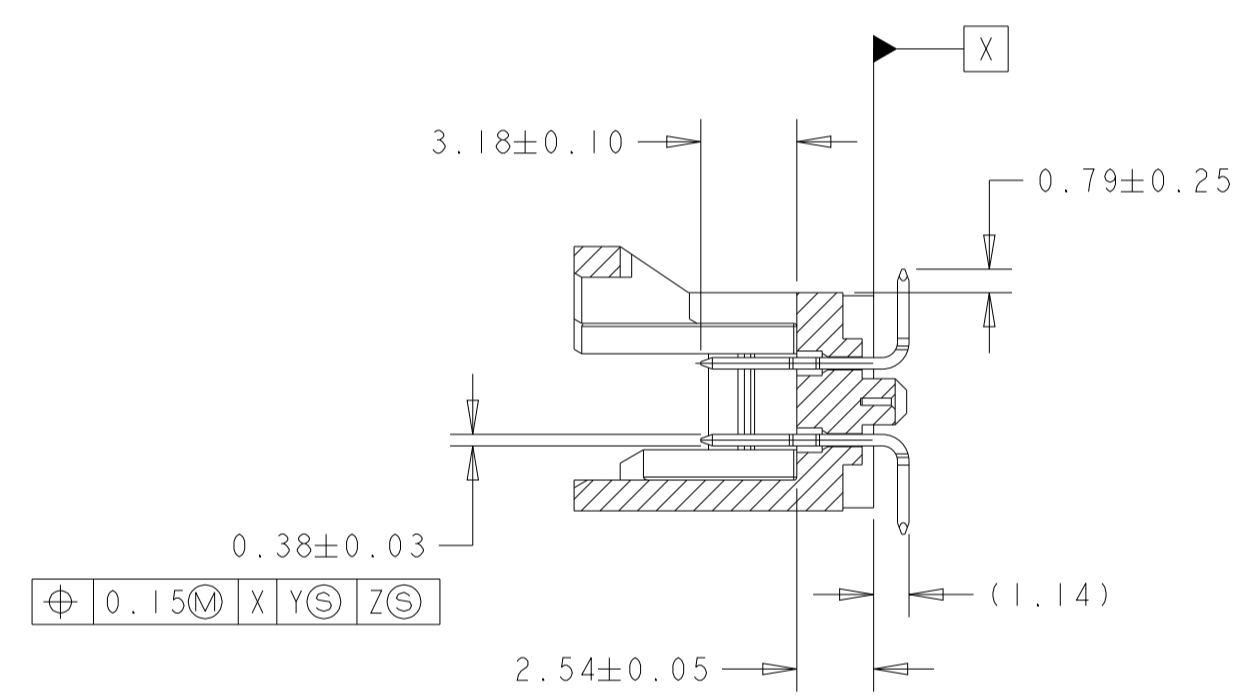
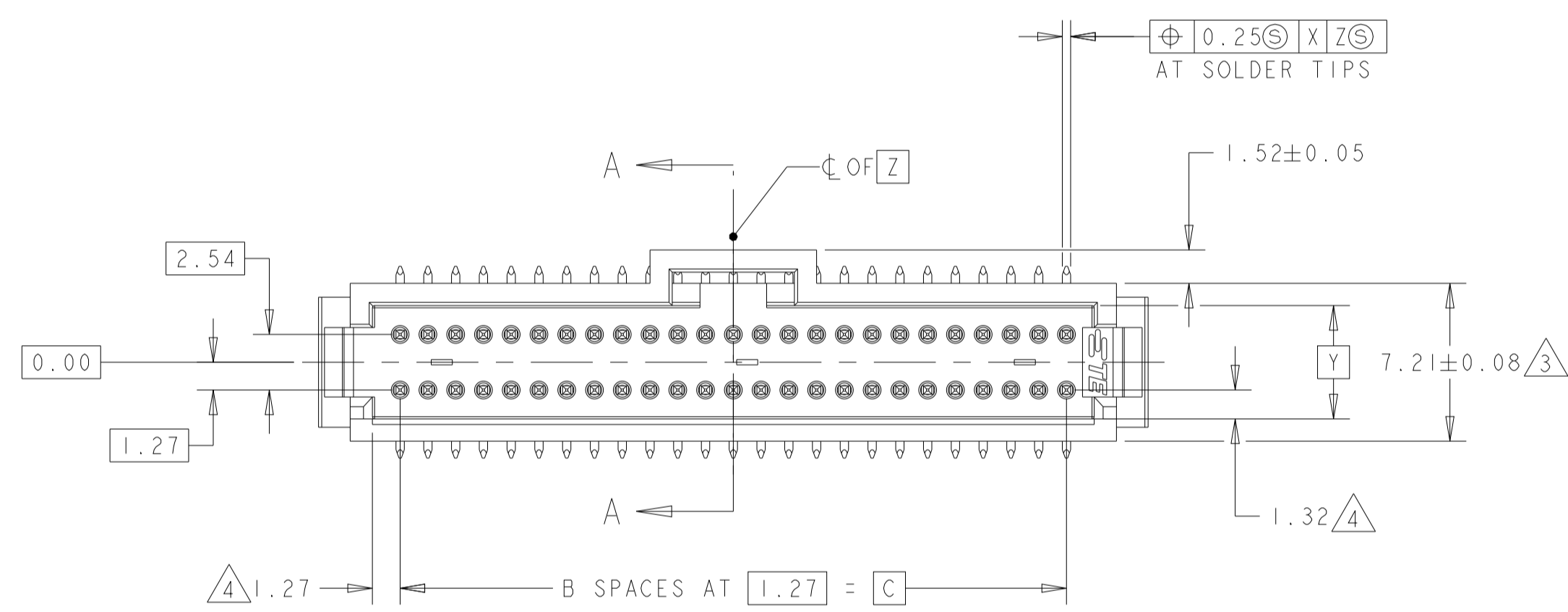


REVISIONS					
P	LTN	DESCRIPTION	DATE	DWN	APVD
E3		REVISED PER ECN-23-197910	22FEB2023	RK	MF

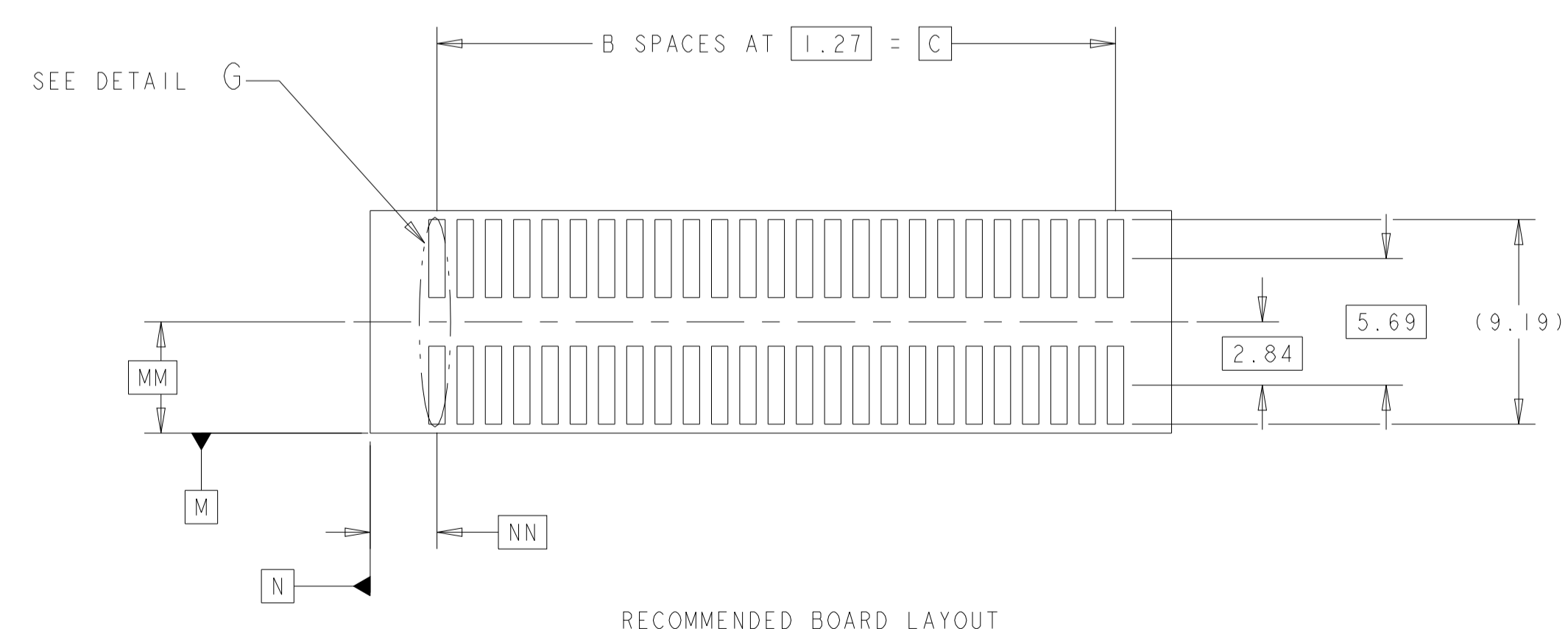


BASIC DIMENSIONS FOR EVEN NUMBER OF SPACES (SEE TABLE) SCALE 6:1

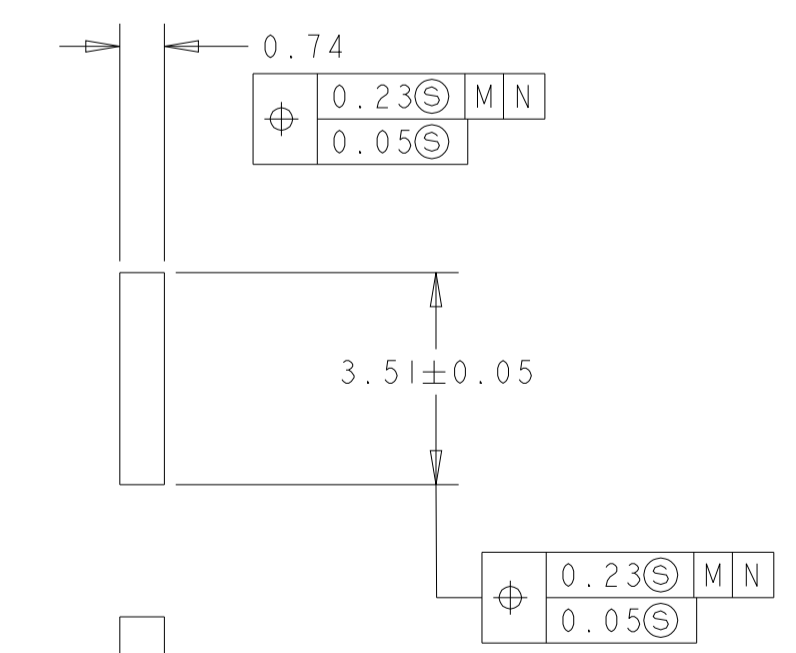
- 1 0.76 μm GOLD IN LOCALIZED PLATE AREA, 3.81 μm TIN ON SOLDER TAILS ALL OVER 1.27 μm NICKEL.
- 2 CIRCUIT IDENTIFICATION FEATURE OMITTED ON 10 POSITION HEADER ASSEMBLIES.
- 3 DIMENSION APPLIES AT BASE OF SHROUD.
- 4 THE NOTED DIMENSIONS APPLY AT THE MATING FACE OF THE HOUSING
- 5. NOTE DELETED.
- 6 HOUSING: BLACK THERMOPLASTIC. CONTACT: COPPER ALLOY.
- 7 FINISH: 0.03 μm MIN GOLD ON GOLD PLATED AREA, 3.81 μm MATTE TIN ON TIN PLATE AREA, UNDER PLATING TO BE 1.27 μm NICKEL ON ENTIRE CONTACT, GOLD AND TIN PLATING MAY NOT OVERLAP.
- 8. DELETED.
- 9 PACKAGED IN TAPE AND REEL PER EIA 481 SPECIFICATIONS



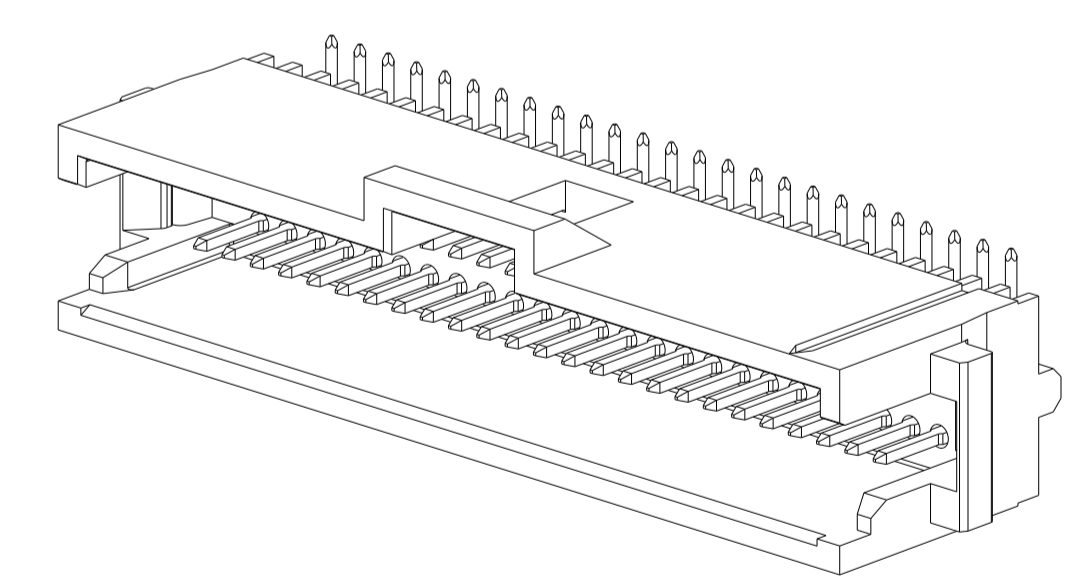
SECTION A-A



RECOMMENDED BOARD LAYOUT



DETAIL G SCALE 8:1



FINISH	TAPE WIDTHS	DIM.C	B SPACES	DIM.A	NO OF POSN	PART NUMBER	
△		56 mm	17.78	14	22.35	30	3-1825601-0
△		56 mm	30.48	24	35.05	50	2-1825601-1
△		44 mm	11.43	9	16.00	20	2-1825601-0
△		56 mm	30.48	24	35.05	50	1825601-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm

TOLERANCES UNLESS OTHERWISE SPECIFIED:

0 PLC	±	
1 PLC	±0.3	
2 PLC	±0.13	
3 PLC	±	
4 PLC	±	
ANGLES	±	±0.5°

MATERIAL: △ 6

SEE TABLE

CUSTOMER DRAWING

DWN: R. SHRISHAIL 05DEC2017
CHK: J. OLSON 05DEC2017
APVD: J. OLSON 05DEC2017

NAME: HEADER ASSEMBLY, W/SIDE & END LATCHES, VERTICAL, SHROUDED, DOUBLE ROW, SURFACE MOUNT, W/O HOLD-DOWNS, AMPMODU System 50

PRODUCT SPEC: 108-1093
APPLICATION SPEC: 114-25035

SIZE: A | 00779 | C=1825601 | SHEET 1 OF 1 | REV E3

SCALE: 4:1